



MMBT2222ALP4

40V NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

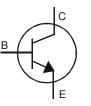
- Low Collector-Emitter Saturation Voltage, V_{CE(sat)}
- Ultra-Small Leadless Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

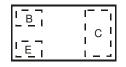
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 @
- Weight: 0.0009 grams (Approximate)

X2-DFN1006-3

Bottom View



Device Symbol



Top View Device Schematic

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMBT2222ALP4-7B	2S	7	8	10,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

2S = Product Type Marking Code

Bar Denotes Base and Emitter Side

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



Top View



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	75	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current - Continuous	Ι _C	600	mA
Peak Collector Current	I _{CM}	800	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	460	mW
Power Dissipation (Note 6)	PD	1	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	272	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{0JA}	120	°C/W
Thermal Resistance, Junction to Lead (Note 7)	R _{0JL}	110	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

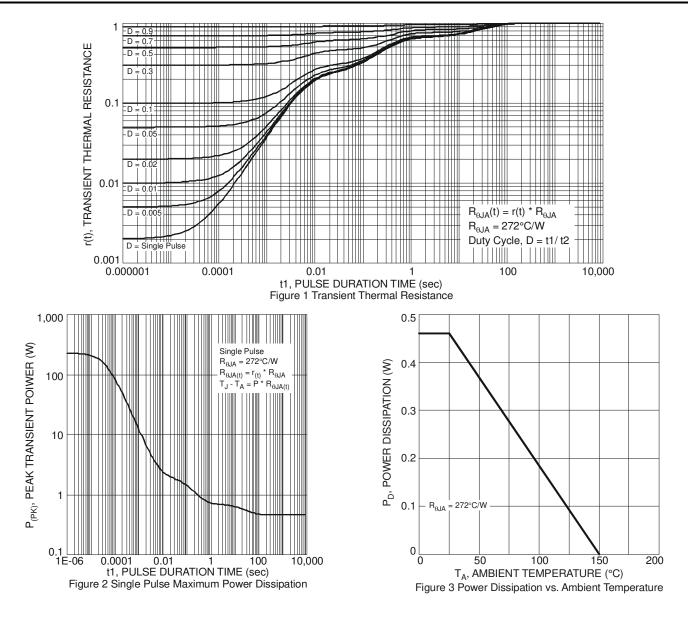
ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	≥ 8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С

Notes: 5. For a device surface mounted on minimum recommended pad layout FR-4 PCB with single sided 1oz copper, in still air conditions; the device is To a device strate inclusion of minimum recommended pad sport (14-4 CB with single state 102 copper, in stim measured when operating in a steady-state condition. The entire exposed collector pad is attached to the heatsink.
Same as note 5, except device is surface mounted on 25mm X 25mm collector pad heatsink with 1oz copper.
Thermal resistance from junction to solder-point (at the end of the collector lead).
Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics





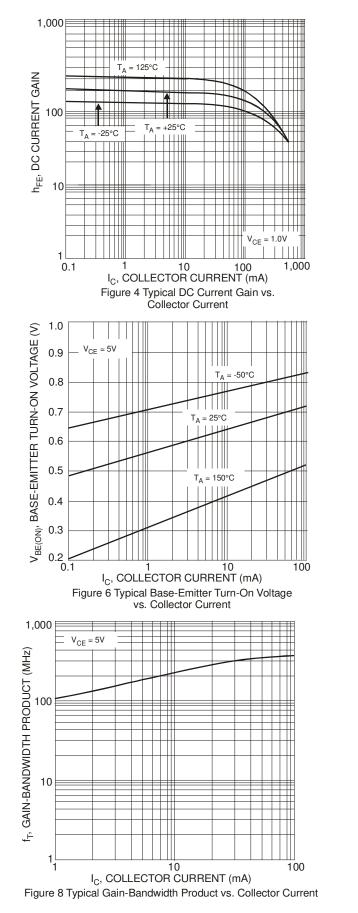
Electrical Characteristics (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

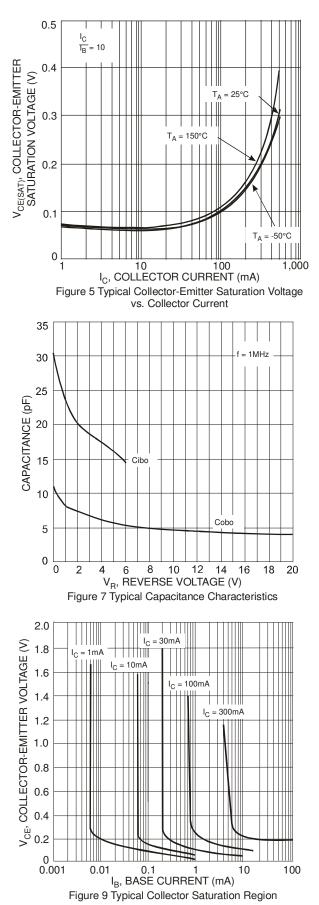
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						Test condition
Collector-Base Breakdown Voltage	BV _{CBO}	75		_	V	$I_{\rm C} = 100 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 6)	BVCEO	40		_	V	$I_{\rm C} = 100 \text{A}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BVEBO	6			V	$I_{\rm F} = 100\mu A, I_{\rm C} = 0$
Collector Cutoff Current	ICEX	_		10	nA	$V_{CE} = 60V, V_{EB(off)} = 3V$
	I _{CBO}	_		10	nA	$V_{CB} = 60V, I_E = 0$
Collector Cutoff Current				10	μA	$V_{CB} = 60V, I_E = 0, T_A = +125^{\circ}C$
Emitter Cutoff Current	I _{EBO}			10	nA	$V_{EB} = 5V, I_{C} = 0$
Base Cutoff Current	I _{BL}			20	nA	$V_{CE} = 60V, V_{EB(off)} = 3V$
ON CHARACTERISTICS (Note 6)						
		35		_	_	$V_{CE} = 10V, I_C = 0.1mA$
		50	_	_	_	$V_{CE} = 10V, I_{C} = 1mA$
		75		_	_	$V_{CE} = 10V, I_{C} = 10mA$
DC Current Gain	h _{FE}	35				$V_{CE} = 10V, I_{C} = 10mA, T_{A} = -55^{\circ}C$
		100		300	_	V _{CE} = 10V, I _C = 150mA
		50				$V_{CE} = 1V, I_{C} = 150mA$
		40				$V_{CE} = 10V, I_C = 500mA$
Collector-Emitter Saturation Voltage	Maria a	_		0.3	1.0 V	$I_{C} = 150 \text{mA}, I_{B} = 15 \text{mA}$
	V _{CE(sat)}	_	—			$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}$
Base-Emitter Saturation Voltage	V _{BE(sat)}	0.6		1.2	v	$I_{C} = 150 \text{mA}, I_{B} = 15 \text{mA}$
5		_		2.0	v	$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}$
SMALL SIGNAL CHARACTERISTICS (Note 6)	i		i		i	
Output Capacitance	Cobo	_		8	pF	$V_{CB} = 10V, f = 1.0MHz, I_E = 0$
Input Capacitance	C _{ibo}			25	pF	$V_{EB} = 0.5V, f = 1.0MHz, I_{C} = 0$
Current Gain-Bandwidth Product	f _T	300		_	MHz	$V_{CE} = 20V, I_C = 20mA, f = 100MHz$
Noise Figure	NF	_	—	4.0	dB	V_{CE} = 10V, I_C = 100µA, R_S = 1.0k Ω , f = 1.0kHz
Input Impedance	h _{ie}	0.25		1.25	kΩ	
Voltage Feedback Ratio	h _{re}			4.0	X 10 ⁻⁴	$1 = 10 \text{ m} \text{ A} \text{ V}_{} = 10 \text{ V}_{} \text{ f} = 10 \text{ kHz}$
Small-Signal Current Gain	h _{fe}	75		375	_	I _C = 10mA, V _{CE} = 10V, f = 1.0kHz
Output Admittance	h _{oe}	25		200	μS	
SWICHING CHARACTERISTICS (Note 6)					-	· · · · · · · · · · · · · · · · · · ·
Delay Time	t _d			10		$V_{CC}=30V,\ V_{BE(off)}=-0.5V,$
Rise Time	tr	—	—	25	nS	$I_{C} = 150 \text{mA}, I_{B1} = 15 \text{mA}$
Storage Time	ts	—		225		$V_{CC} = 30V, I_C = 150mA,$
Fall Time	t _f	_		60		$I_{B1} = I_{B2} = 15 \text{mA}$

Notes: 6. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



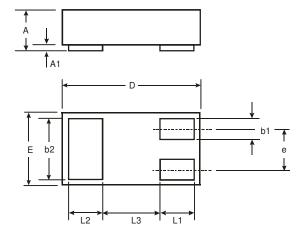
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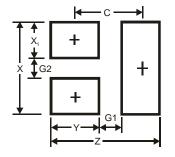


Package Outline Dimensions



X2-DFN1006-3					
Dim	Min	Max	Тур		
Α	_	0.40	_		
A1	0	0.05	0.03		
b1	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	-	_	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3			0.40		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)		
Z	1.1		
G1	0.3		
G2	0.2		
Х	0.7		
X1	0.25		
Y	0.4		
С	0.7		



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